FINEPLACER® CRS 10

Compact Rework System

Micro Assembly | Advanced Rework | FINEPLACER® CRS 10

BGA • CGA • CBGA • µBGA • CSP • QFP • TSOP • PLCC • Small Passive • RF Shields • Connectors

Features

- Placement accuracy better than 10 microns
- Patented Vision Alignment System (VAS) with stationary beam splitter
- **Co**ntrolled **Mi**xed **S**oldering **S**ystem - **COMISS** Windows® based graphic user interface, „CompactReflow Pro“
- Automated component place and LIFT-OFF function
- Controlled Z-HEIGHT during reflow
- Small foot print
- Quick set up and easy to operate
- Reliable rework process
- Proven soldering head technology
- Lead-free compatible rework

Placement and Reflow of new component — Component Removal

Solder Paste Printing — Residual Solder Removal

come in and learn more
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...simply accurate

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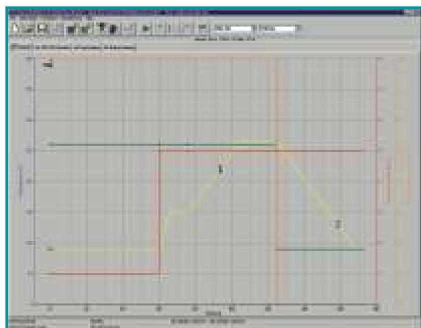
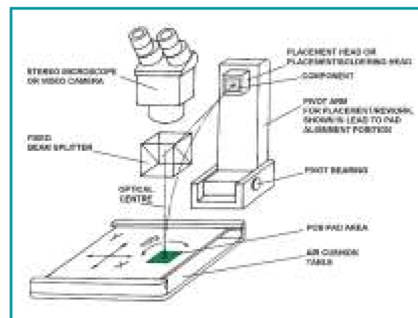

Graphic User Interface

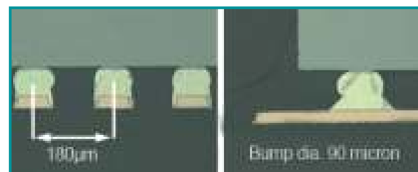
Vision Alignment System
- Patented VAS design with stationary beam splitter
- Simultaneous representation of the components contact and substrates pad by means of the beam splitter
- Placement accuracy better than 10 microns
- Only one moving component
- Rapid coarse and fine positioning using air cushion positioning table and adjustment screws



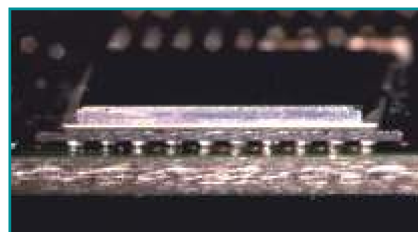
VAS - Working Principle

Residual Solder Removal

Advanced Process Control
- **Co**ntrolled **Mi**xed **S**oldering **S**ystem – **COMISS**
- Windows®based graphic user interface
- Real time control of temperature and air flow
- Simultaneous observation of the solderingprofile and substrate/ component interface (using Observing and Inspection Video Module and Frame Grabber)
- Fast heating and cooling
- Reliable rework process by advanced process control
- Low thermal mass nozzles ensure Short soldering times and fast temperature ramping



C4 Flip Chip, Bump dia. 90 microns, Cross Sections

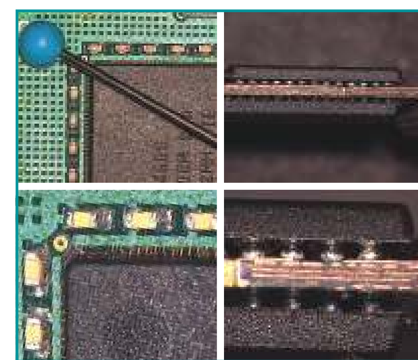

Real Time Process Inspection

RF-Shields | Small Components

Metal BGA

Process Observation
- Real time process observation and inspection with Observing Camera (opt.)

Applications
- BGA, CGA, CSP, µBGA, MLF, QFP, TSOP, PLCC, small components as 0201, 0402 (opt. optics recommended), 0603, connectors
- RF-Shields (single or multiple), Shielding Frame, Flip Chip (C4) rework
- Customized applications


Rework Of High Density Boards

Technical Data		
Max board size	310 x 460 mm	
Heater	top	bottom
max. temperature	380 °C	360°C
max. air flow	70 l/min	160 l/min
max. ramping rate	1...70°C/s	
Facilities		
Power	110, 230 V/2.2 kVA	
Compressed air	6 bar	

Options
Observation and Inspection Video
Split Field Optics, Mirage
Solder Removal Module
Reballing Module
Solder Paste Printing Heads
Board Temperature Sensor ...Tt, Gas Switching...GS
Frame Grabber
Proven soldering head technology

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